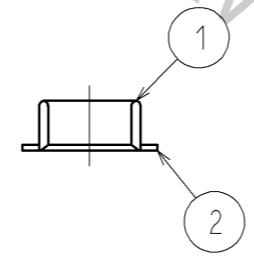
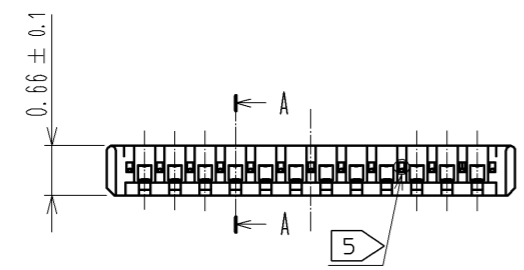
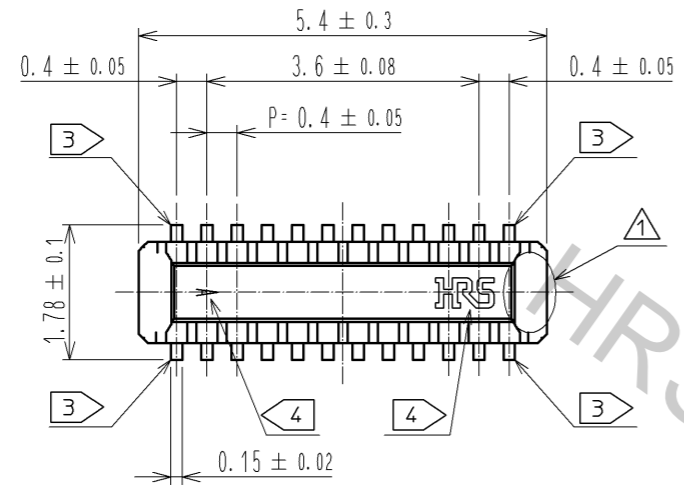
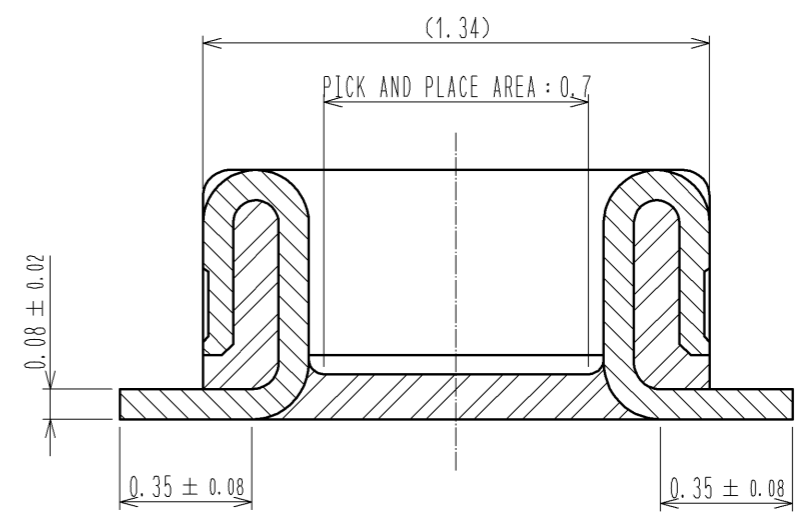


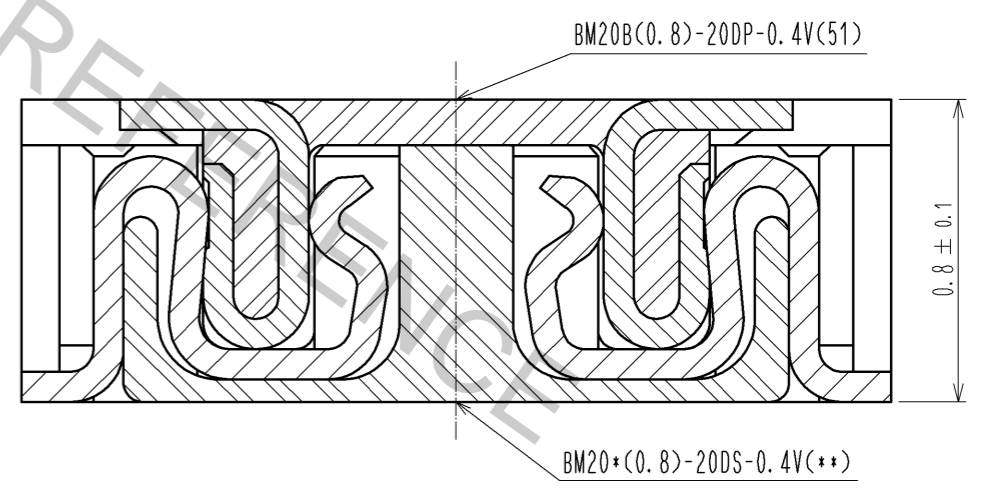
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A-A (50:1)



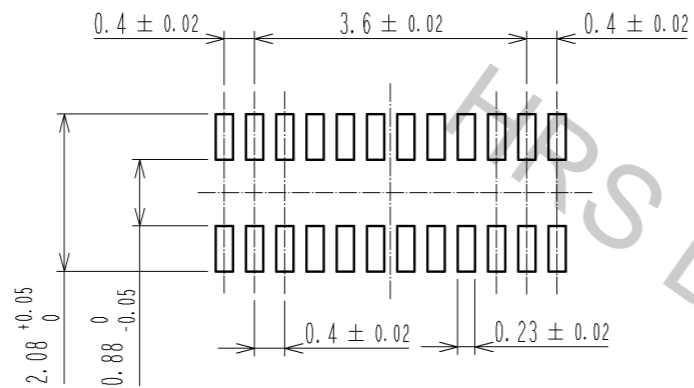
ENGAGEMENT FIGURE (50:1) \triangle



- NOTE 1 . ALL LEAD CO-PLANARITY SHALL BE 0.08mm MAX
- \triangleright CONTACT PLATING SPECIFICATIONS
 CONTACT AREA : GOLD 0.05 μ m MIN
 SMT LEAD : GOLD 0.05 μ m MIN
 UNDER PLATING : NICKEL 1 μ m MIN
 (SURFACE : SEALING)
 - \triangleright EACH CONTACTS AT 4 CORNERS ARE PROVIDED FOR METAL FITTINGS.
 - \triangleright HRS MARK AND CAV No. ARE INDICATED IN APPROX POSITION SHOWN.
 - \triangleright A PART OF THE WALL COULD BE NOTCHED.

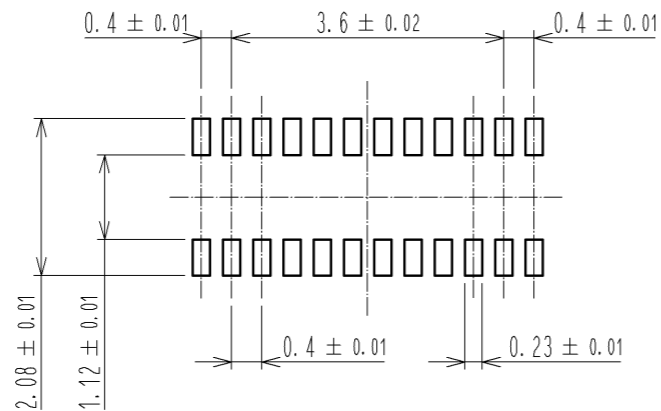
3	PS	CLEAR (EMBOSSED CARRIER TAPE)	6	PS	CLEAR (REINFORCEMENT COLLAR)
2	PHOSPHOR BRONZE	\triangleright	5	PS	BLACK (PLASTIC REEL)
1	LCP	UL94 V-0, BLACK	4	POLYESTER	CLEAR (COVER TAPE)
NO.	MATERIAL	FINISH . REMARKS	NO.	MATERIAL	FINISH . REMARKS
UNITS mm	\odot \triangleleft	SCALE 10 : 1	COUNT \triangle 3	DESCRIPTION OF REVISIONS	
				DESIGNED YK. SATAKE	CHECKED TS. MIYAZAKI
				DATE 12. 01. 07	
HRS HIROSE ELECTRIC CO., LTD.		APPROVED : KH. IKEDA	11. 09. 16	DRAWING NO. EDC3-332308-01	
		CHECKED : TS. MIYAZAKI	11. 09. 16	PART NO. BM20B(0.8)-20DP-0.4V(51)	
		DESIGNED : YK. SATAKE	11. 09. 16	CODE NO. CL684-9002-8-51	
		DRAWN : KR. AJITO	11. 09. 15	\triangle 1/3	

◆ RECOMMENDED PCB LAYOUT

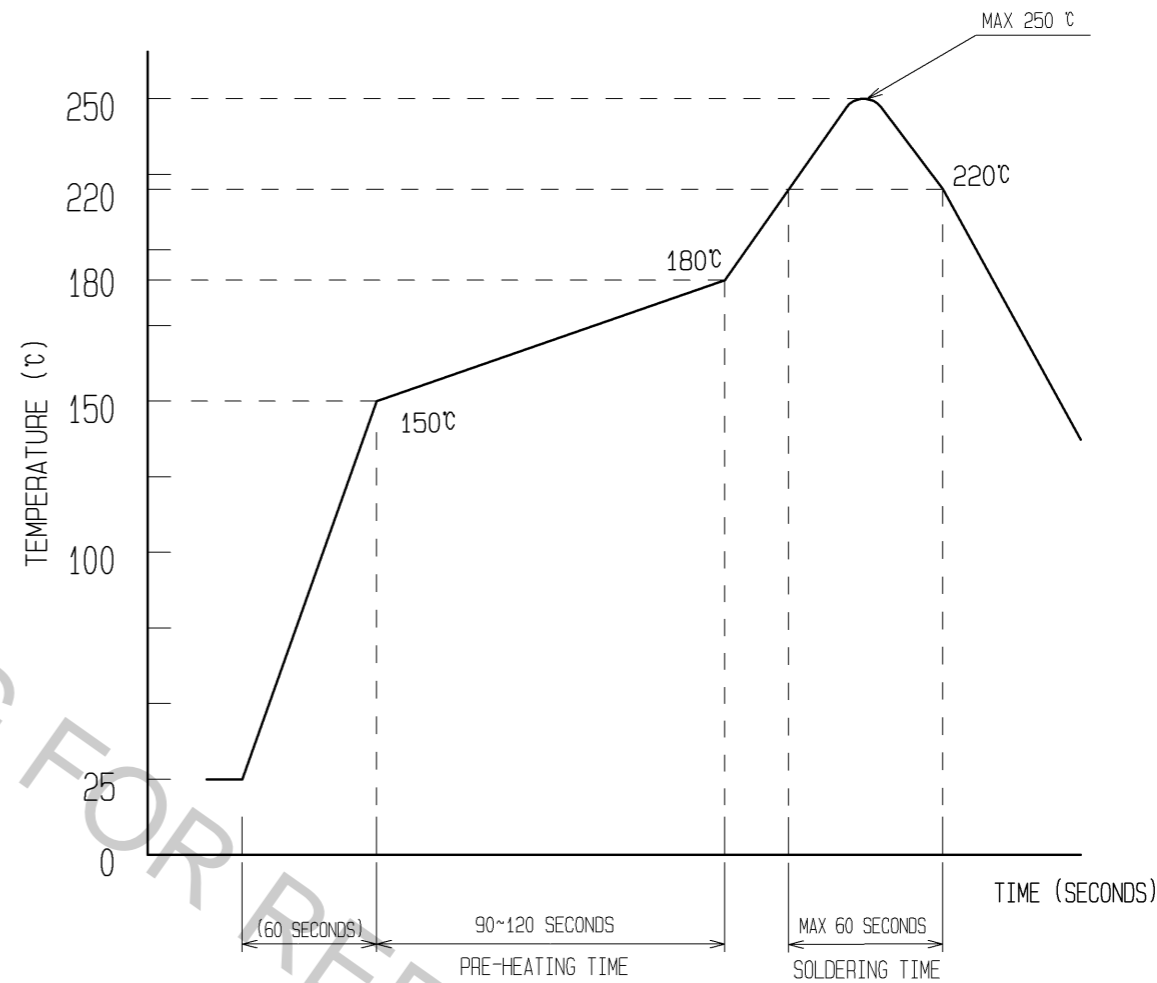


◆ RECOMMENDED METAL MASK DIMENSIONS [△]

METAL MASK THICKNESS : 100 μm



6 RECOMMENDED REFLOW TEMPERATURE PROFILE USING LEAD-FREE SOLDER PASTE.

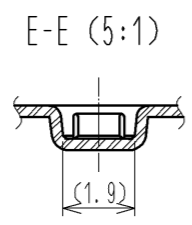
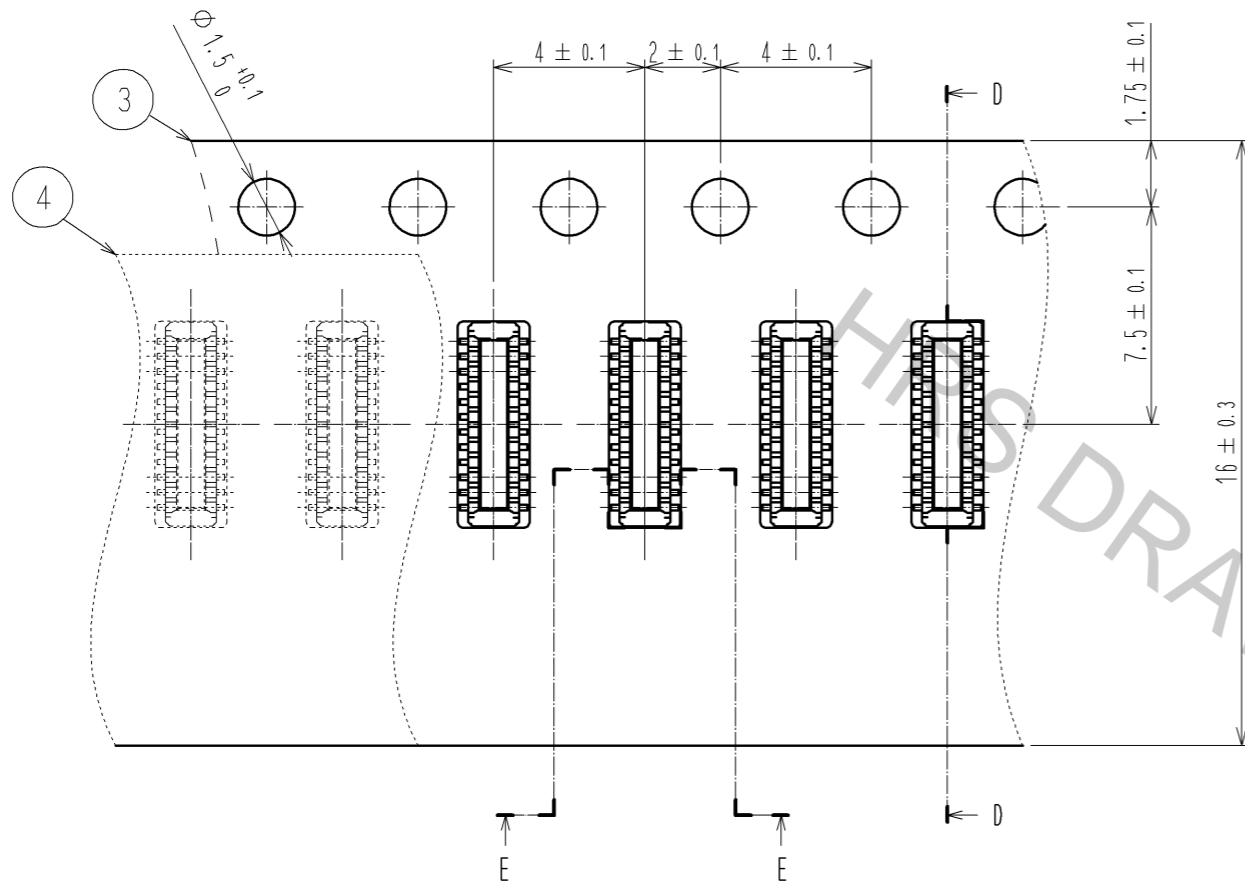


REFLOW METHOD: IR REFLOW
 NUMBER OF REFLOW CYCLES: 2 CYCLES MAX.
 1) REFLOW TIME
 DURATION ABOVE 220°C: 60 SEC MAX.
 (PEAK TEMPERATURE: 250°C MAX)
 2) PRE-HEAT TIME
 PRE-HEAT TEMPERATURE(MIN): 150°C
 PRE-HEAT TEMPERATURE(MAX): 180°C
 PRE-HEAT TIME: 90-120 SEC.

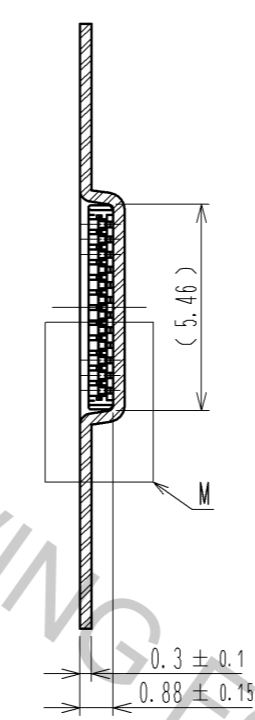
6 THIS TEMPERATURE PROFILE IS PER THE CONDITIONS SHOWN ABOVE. ADDITIONAL FACTORS, SUCH AS SOLDER PASTE TYPE, PCB SIZE AND OTHER MOUNTED COMPONENTS COULD AFFECT THE PROFILE. THEREFORE, A THOROUGH EVALUATION OF MOUNTING COONDITION IS REQUIRED PRIOR TO PRODUCTION. TEPERATURE IS MEASURED AT CONTACT LEAD.

HRS	DRAWING NO.	EDC3-332308-01
	PART NO.	BM20B(0.8)-20DP-0.4V(51)
	CODE NO.	CL684-9002-8-51 [△] 2/3

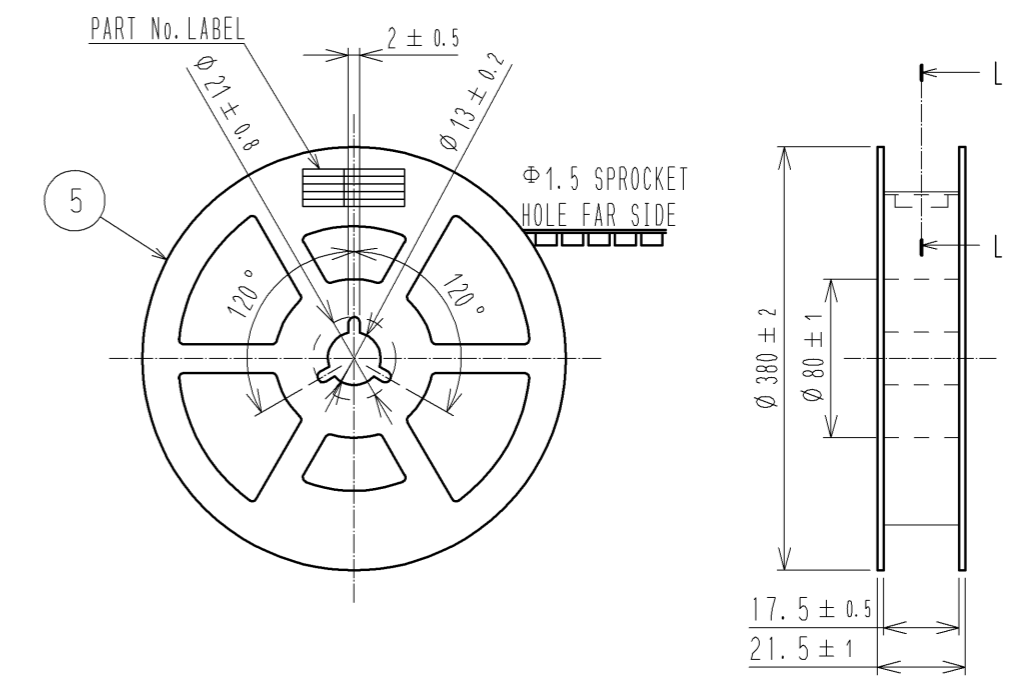
EMBOSED CARRIER TAPE PACKAGING (5:1)



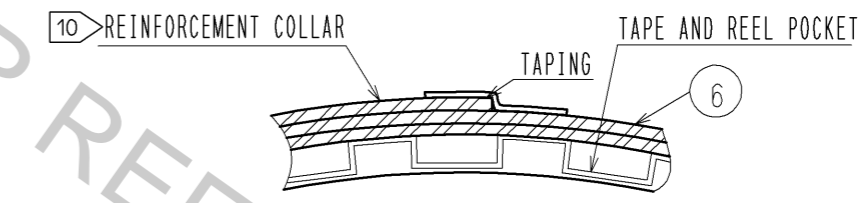
D-D (5:1)



STYLE AND DIMENTION OF REEL (FREE)



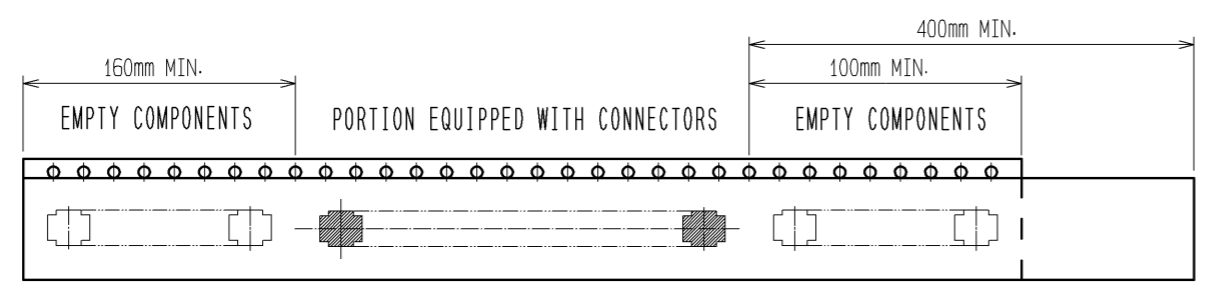
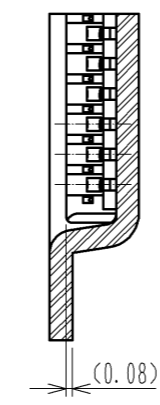
L-L (FREE)



DETAIL OF PART No. LABEL

製造年月日	** ** *	DATE OF MANUFACTURED
製品コード	CL684-9002-8-51	CODE No.
製品名	BM20B(0.8)-20DP-0.4V(51)	PART No.
数量	8,000	QUANTITY
納入者	ヒロセ電機(株)	SUPPLIER

M (10:1)



- 7. PER REEL 8000 CONNECTORS.
- 8. THE DIMENTION IN PARENTHESSES ARE FOR REFERENCE.
- 9. REFER TO JIS C 0806(PACKAGING OF COMPONENTS FOR AUTOMATIC HANDLING)
- 10. AFTER PACKAGING, ROLL 2 METERS OF THE REINFORCEMENT COLLAR TO OUTER CIRCUMFERENCE OF TAPE AND REEL POCKET. AND TAPE DOWN AT THE END THE COLLAR.

HRS	DRAWING NO.	EDC3-332308-01
	PART NO.	BM20B(0.8)-20DP-0.4V(51)
	CODE NO.	CL684-9002-8-51
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